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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/830,049	04/23/2004	Masami Ohnishi	520.43783X00	8728
20457 7590 08/23/2005 ANTONELLI, TERRY, STOUT & KRAUS, LLP 1300 NORTH SEVENTEENTH STREET SUITE 1800 ARLINGTON, VA 22209-3873			EXAMINER	
			NGUYEN, JOHN B	
			ART UNIT	PAPER NUMBER
			2819	:
			DATE MAILED: 08/23/2005	:
				:

Please find below and/or attached an Office communication concerning this application or proceeding.

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v.

	Application No.	Applicant(s)				
	10/830,049	OHNISHI ET AL.				
Office Action Summary	Examiner	Art Unit				
·	John B. Nguyen	2819				
The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with the c	orrespondence address				
A SHORTENED STATUTORY PERIOD FOR REPL' THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.1: after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply - If NO period for reply is specified above, the maximum statutory period of the period of the period for reply within the set or extended period for reply will, by statute - Any reply received by the Office later than three months after the mailing - earned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be tin y within the statutory minimum of thirty (30) day will apply and will expire SIX (6) MONTHS from , cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on	· 					
2a) This action is FINAL . 2b) ☐ This	n) This action is FINAL . 2b) ⊠ This action is non-final.					
• •	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims						
4) ☐ Claim(s) 1-7 is/are pending in the application. 4a) Of the above claim(s) is/are withdraw 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-7 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or						
Application Papers						
9)☐ The specification is objected to by the Examine						
10)⊠ The drawing(s) filed on <u>23 April 2004</u> is/are: a)⊠ accepted or b)□ objected to by the Examiner.						
Applicant may not request that any objection to the	7,7	, ,				
Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Ex		•				
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document: 2. Certified copies of the priority document: 3. Copies of the certified copies of the priority application from the International Bureau * See the attached detailed Office action for a list	s have been received. s have been received in Applicati rity documents have been receive u (PCT Rule 17.2(a)).	ion No ed in this National Stage				
Attachment(s)						
1) Notice of References Cited (PTO-892)	4) Interview Summary					
 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 04/23/2004. 	Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:	ate Patent Application (PTO-152)				

DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

- (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.
- 2. Claims 1-7 are rejected under 35 U.S.C. 102(e) as being anticipated by Ichitsubo et al. U.S. Patent No. 6,774,718 B2.
- 3. Regarding to claims 1 and 7, Figures 1-4, Ichitsubo et al. discloses a radio frequency amplifier module comprising: a module substrate (fig.4); a radio frequency power amplifier part which is arranged on the module substrate and amplifies a power of a radio frequency signal (fig.1); a bias control part which is arranged on the module substrate and controls operation of the radio frequency power amplifier part with a bias voltage (Bias Circuit 22); and a bias supply line for supplying the bias voltage from the bias control part to the radio frequency power amplifier part (fig.1), wherein the bias supply line includes at least one bonding pad having a capacitance component to a ground and a bonding wire formed via the at least one bonding pad (fig.4).
- 4. Regarding to claim 2, wherein the radio frequency power amplifier part is constituted as a semiconductor integrated circuit (fig. 1) formed on a semiconductor substrate (fig. 4) and the bias

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supply line (fig.1) is formed on the semiconductor substrate.

5. Regarding to claim 3, wherein the bias control part constituted as a semiconductor integrated circuit (fig. 1) formed on a semiconductor substrate (fig. 4) and the bias supply line (fig. 1) is formed on the semiconductor substrate.

6. Regarding to claim 4, wherein the radio frequency power amplifier part and the bias control part are constituted as a semiconductor integrated circuit (fig.1) formed on the same semiconductor substrate (fig.4) and the bias supply line (fig.1) is formed on the semiconductor substrate.

- 7. Regarding to claim 5, wherein the bias supply line is formed on the module substrate (fig.4).
- 8. Regarding to claim 6, further comprising: a second substrate formed on the module substrate, wherein one part of a plurality of bonding pads included in the at least one bonding pad is formed on the module substrate and the other part of the plurality of bonding pads is formed on the second substrate (fig.4).

Conclusion

9. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. (See enclosed Form PTO-892).

Any inquiry concerning this communication or earlier communications from the examiner should be directed to John B Nguyen whose telephone number (571) 272-1808. The examiner can normally be reached on 8AM-4: 30 PM M-F.

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John B. Nguyen August 20, 2005

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